

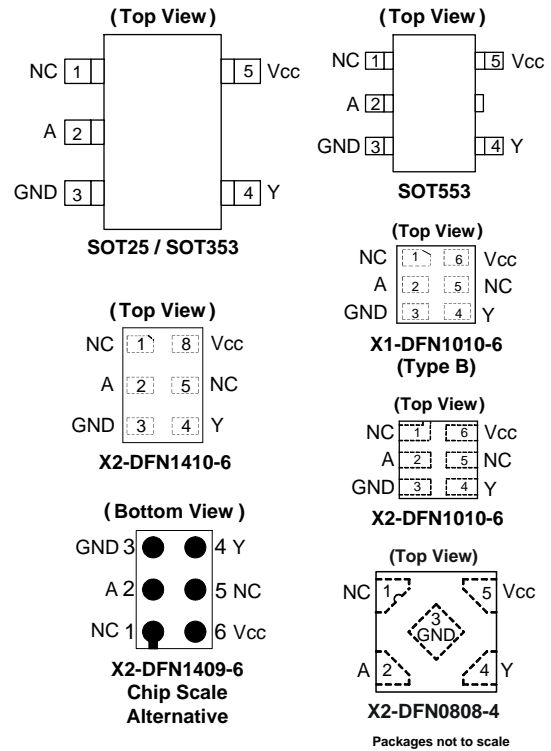
Description

The 74LVC1G06 is a single inverter gate with an open drain output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The input is tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. The open-drain output can be connected to other open drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32mA.

Features

- Wide Supply Voltage Range from 1.65 to 5.5V
- 24mA Sink Current at 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115)
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Pin Assignments

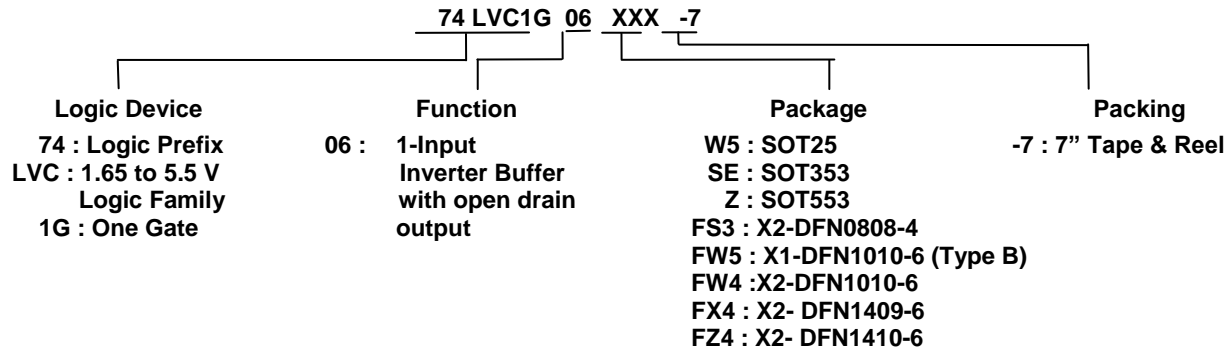


Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Tablet Computers, E-readers
 - Computer Peripherals, Hard Drives, CD/DVD ROM
 - TV, DVD, DVR, Set Top Box
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

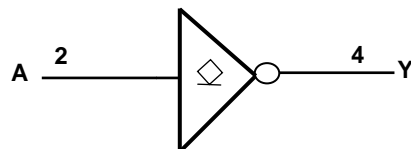
Ordering Information (Note 4)


Part Number	Package Code	Package (Notes 5 & 6)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G06W5-7	W5	SOT25	3.0mm x 2.8mm x 1.2mm 0.95 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G06SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74LVC1G06Z-7	Z	SOT553	1.6mm x 1.6 mm x 0.62mm 0.5 mm lead pitch	4,000/Tape & Reel	-7
74LVC1G06FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8 mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74LVC1G06FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G06FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G06FX4-7	FX4	X2-DFN1409-6 Chip scale alternative	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74LVC1G06FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

- Notes:
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.
 5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 6. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Description
NC	No Connection
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram

Function Table

Inputs	Output
A	Y
H	L
L	Z

Absolute Maximum Ratings (Notes 7 & 8) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High or Low State.	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GN}	Continuous Current Through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 9) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5	—	V
V _{IH}	High-Level Input Voltage	V _{CC} = 1.65V to 1.95V	0.65 x V _{CC}	—	V
		V _{CC} = 2.3V to 2.7V	1.7	—	
		V _{CC} = 3V to 3.6V	2	—	
		V _{CC} = 4.5V to 5.5V	0.7 x V _{CC}	—	
V _{IL}	Low-Level Input Voltage	V _{CC} = 1.65V to 1.95V	—	0.35 x V _{CC}	V
		V _{CC} = 2.3V to 2.7V	—	0.7	
		V _{CC} = 3V to 3.6V	—	0.8	
		V _{CC} = 4.5V to 5.5V	—	0.3 x V _{CC}	
V _I	Input Voltage	0	5.5	V	
V _O	Output Voltage	0	5.5	V	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 2.7V	—	12	
		V _{CC} = 3V	—	16	
		V _{CC} = 4.5V	—	24	
		V _{CC} = 4.5V	—	32	
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V	—	20	ns/V
		V _{CC} = 3.3V ± 0.3V	—	10	
		V _{CC} = 5V ± 0.5V	—	5	
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 9. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	-40°C to +85°C			-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V_{OL}	Low Level Output Voltage	$I_{OL} = 100\mu A$	1.65V to 5.5V	—	—	0.1	—	0.1	V
		$I_{OL} = 4mA$	1.65V	—	—	0.45	—	0.7	
		$I_{OL} = 8mA$	2.3V	—	—	0.3	—	0.45	
		$I_{OL} = 12mA$	2.7	—	—	0.4	—	0.6	
		$I_{OL} = 16mA$	3V	—	—	0.4	—	0.6	
		$I_{OL} = 24mA$		—	—	0.55	—	0.8	
		$I_{OL} = 32mA$	4.5V	—	—	0.55	—	0.8	
I_I	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V	—	± 0.1	± 5	—	± 100	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0V	—	—	± 10	—	± 200	μA
I_{CC}	Supply Current	$V_I = 5.5V$ or GND $I_O = 0$	5.5V	—	0.1	10	—	200	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6V$	3V to 5.5V	—	—	500	—	5,000	μA
C_i	Input Capacitance	$V_i = V_{CC}$ or GND	3.3V	—	5	—	—	—	pF

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ.	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 10)	—	204	—	$^\circ C/W$
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6 (Type B)		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 10)	—	52	—	$^\circ C/W$
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6 (Type B)		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 10. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

Figure 1 Typical Values at $T_A = +25^\circ C$ and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

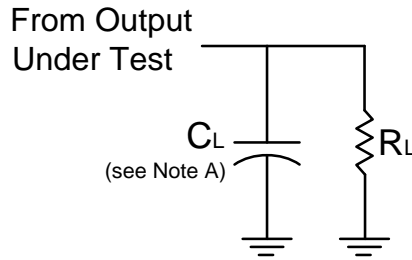
Parameter	From Input	To Output	V _{CC}	$T_A = -40^\circ C$ to $+85^\circ C$			$T_A = -40^\circ C$ to $+125^\circ C$		Unit
				Min	Typ	Max	Min	Max	
t_{pd}	A or B	Y	1.8V \pm 0.15V	1.0	3.0	6.5	1.0	8.5	ns
			2.5V \pm 0.2V	0.5	1.9	4.0	0.5	5.5	
			2.7V	0.5	2.5	4.5	0.5	6.0	
			3.3V \pm 0.3V	0.5	2.3	4.0	0.5	5.5	
			5.0V \pm 0.5V	0.5	1.7	3.0	0.5	4.0	

Operating Characteristics

$T_A = +25^\circ C$

Parameter		Test Conditions	V _{CC} = 1.8V	V _{CC} = 2.5V	V _{CC} = 3.3V	V _{CC} = 5V	Unit
			Typ	Typ	Typ	Typ	
C_{pd}	Power Dissipation Capacitance	f = 10MHz	3	3	4	6	pF

Parameter Measurement Information



V _{CC}	Inputs		V _M	V _{LOAD}	C _L	R _L	V _Δ
	V _I	t _r /t _f					
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	2 X V _{CC}	30pF	1KΩ	0.15V
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	2 X V _{CC}	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	2 X V _{CC}	50pF	500Ω	0.3V

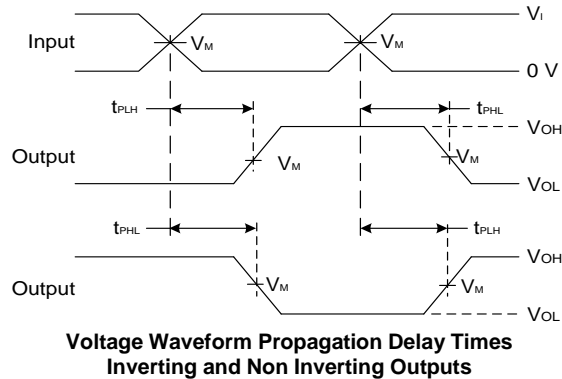
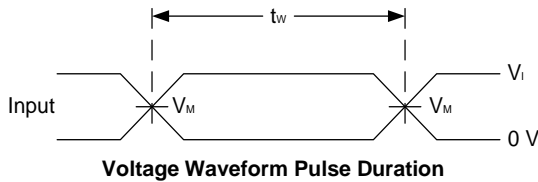
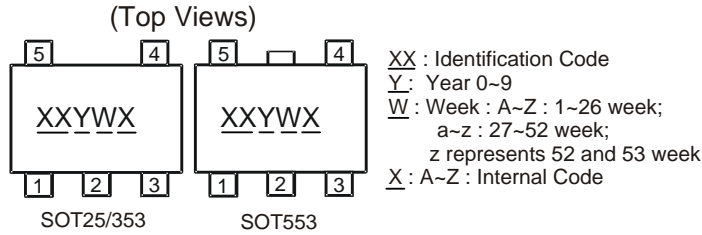


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
 - C. The inputs are measured one at a time with one transition per measurement.
 - D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD}
 - E. t_{PZL} is measured at V_M.
 - F. t_{PLZ} is measured at V_{OL} + V_Δ

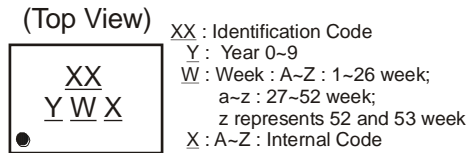
Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G06W5-7	SOT25	UM
74LVC1G06SE-7	SOT353	UM
74LVC1G06Z-7	SOT553	UM

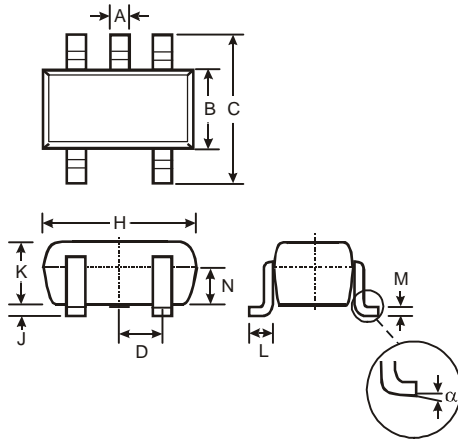
(2) DFN Packages



Part Number	Package	Identification Code
74LVC1G06FS3-7	X2-DFN0808-4	WM
74LVC1G06FW5-7	X1-DFN1010-6 (Type B)	V5
74LVC1G06FW4-7	X2-DFN1010-6	UM
74LVC1G06FX4-7	X2-DFN1409-6	MD
74LVC1G06FZ4-7	X2-DFN1410-6	UM

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

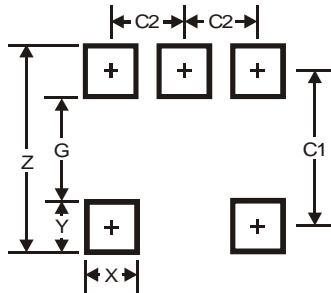


SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT25

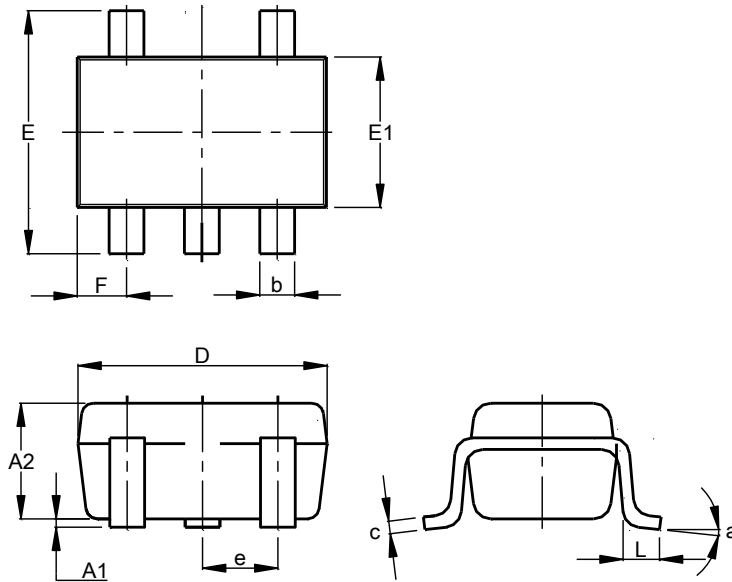


Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT353

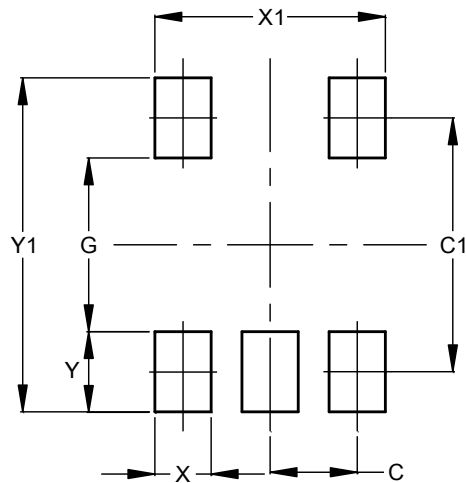


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT353

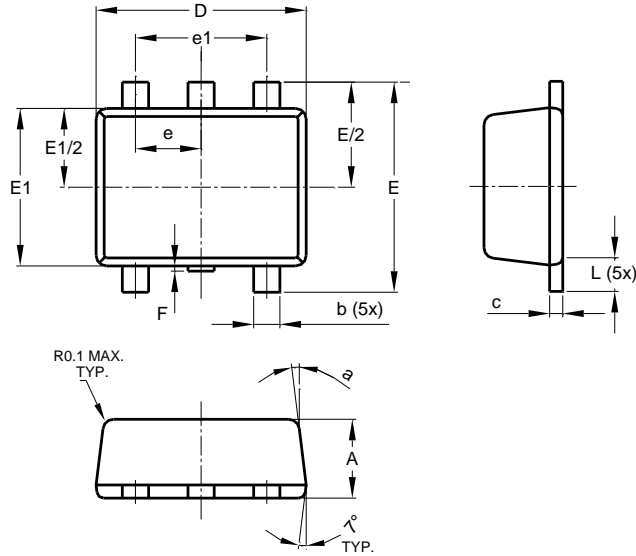


Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT553

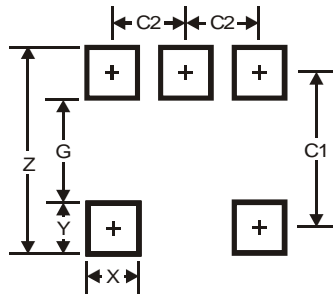


SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT553

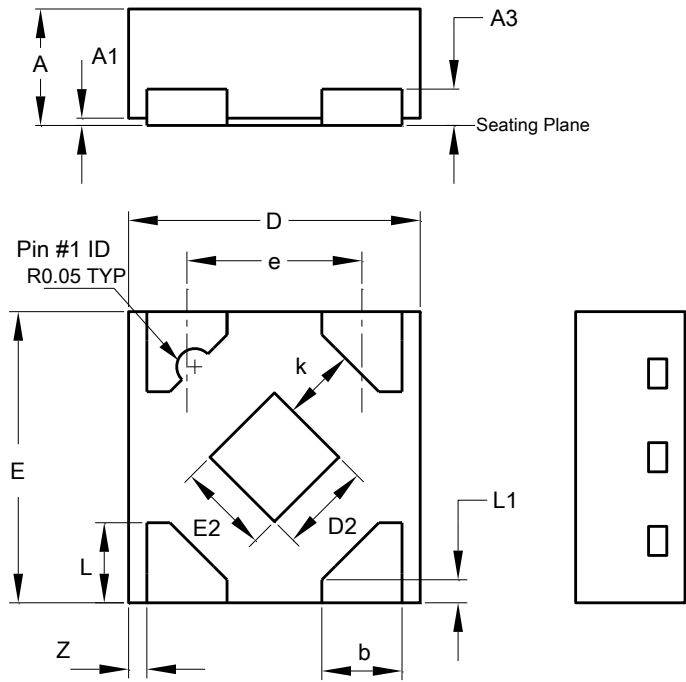


Dimensions	Value
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4

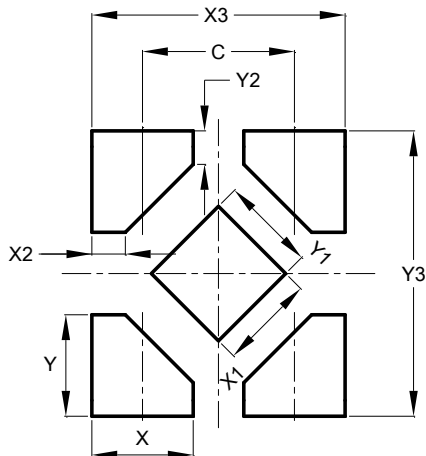


X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN0808-4

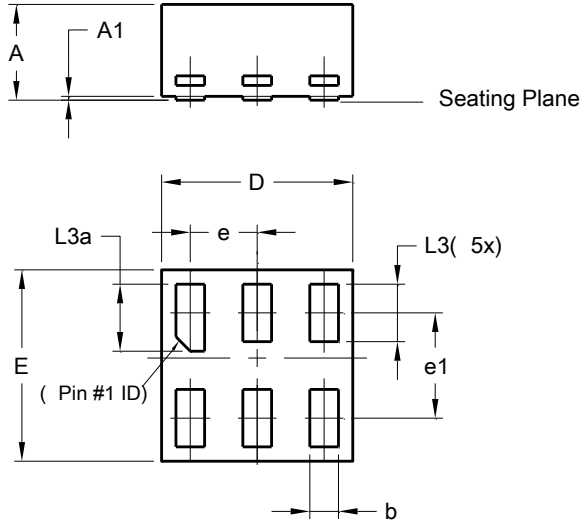


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1010-6 (Type B)

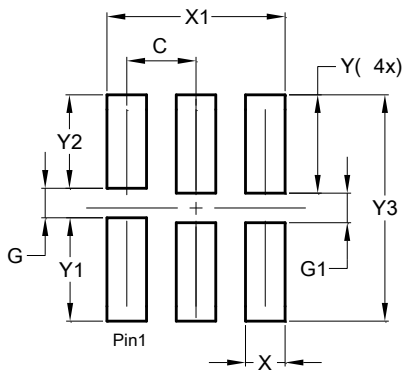


X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1010-6 (Type B)

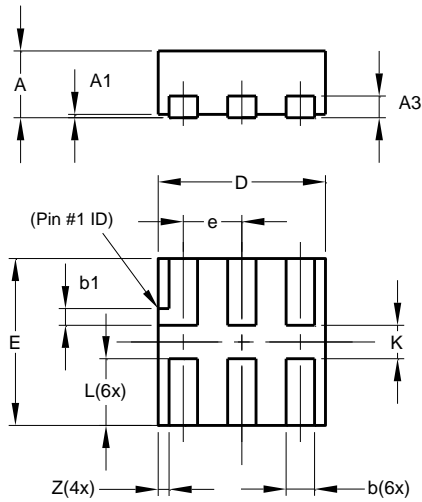


Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

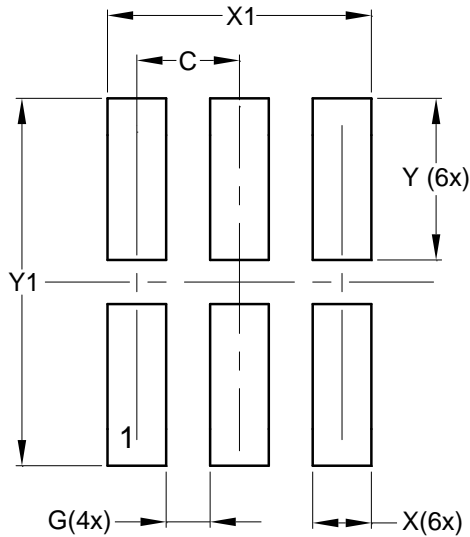


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

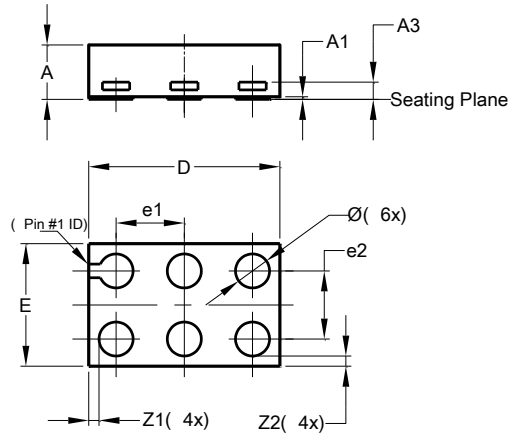


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1409-6 CHIP SCALE ALTERNATIVE



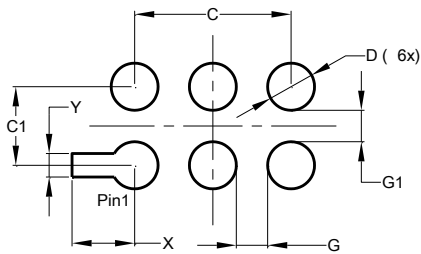
X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1409-6 CHIP SCALE ALTERNATIVE

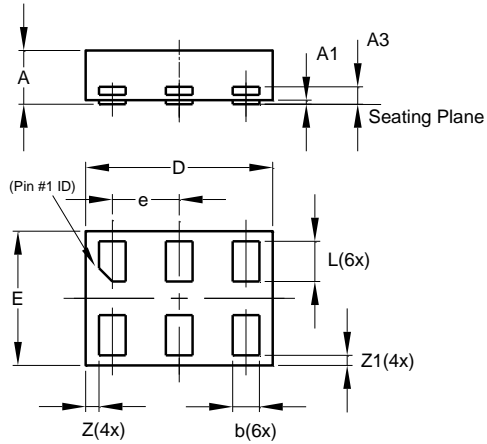


Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6

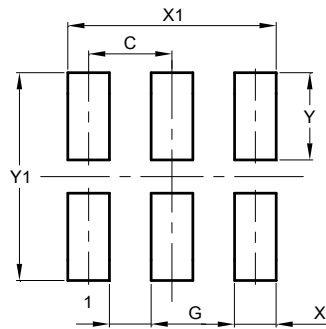


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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